## **EUROPEAN PATENT OFFICE**

## Patent Abstracts of Japan

**PUBLICATION NUMBER** 

2000223861

**PUBLICATION DATE** 

11-08-Q0

APPLICATION DATE

01-02-99

APPLICATION NUMBER

11023545

APPLICANT: MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR: OKADA HIRONOBU;

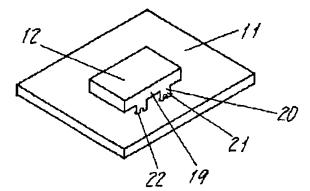
INT.CL.

: H05K 7/12 // H05K 1/18

TITLE

SOLDERING STRUCTURE OF

**ELECTRONIC APPARATUS** 



ABSTRACT: PROBLEM TO BE SOLVED: To improve the reliability of the attachment of a high frequency unit of which an electronic apparatus is composed.

> SOLUTION: An electronic apparatus has a mother printed board 11 on which electronic components are mounted, a frame 19 to which the mother printed board 11 is attached, a plurality of legs 20 provided on the lower part of the frame 19 and pairs of protrusions 21 formed on the respective tips of the legs 20. Through-holes 22 into which the protrusions 21 are inserted are formed in the mother printed board 11. With this constitution, the reliability of the attachment of a high frequency unit 12 of which the electronic apparatus is composed can be improved.

COPYRIGHT: (C)2000, JPO